



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*


Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-10-20
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
LD1085P	RZUX*LUADFC2	A	SHENZHEN B/E	2015-10-20
	Amount	UoM	Unit type	ST ECOPACK Grade
	1700.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10, 9, 4.4	3	THROUGH HOLE	
Comment	TO 220 ISOL FULL PACK 0.5			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	RZUX*LUADFC2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	6.611	mg	supplier	die	Silicon (Si)	7440-21-3		6.454	mg	976252	3796
				supplier	metallization	Aluminium (Al)	7429-90-5		0.060	mg	9076	35
				supplier	Passivation	Silicon Nitride	12033-89-5		0.021	mg	3177	12
				supplier	Passivation	Silicon Oxide	7631-86-9		0.029	mg	4387	17
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.004	mg	605	2
				supplier	back side metallization	Gold (Au)	7440-57-5		0.010	mg	1513	6
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.033	mg	4992	19
Leadframe	Copper & its alloys	592.341	mg	supplier	alloy	Copper (Cu)	7440-50-8		591.571	mg	998700	347983
				supplier	alloy	Iron (Fe)	7439-89-6		0.592	mg	999	348
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.178	mg	301	105
Soft solder	Solder	4.867	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.648	mg	955003	2734
				supplier	solder	Silver (Ag)	7440-22-4		0.122	mg	25067	72
				supplier	solder	Tin (Sn)	7440-31-5		0.097	mg	19930	57
Bonding wires	Other inorganic materials	0.489	mg	supplier	wire	Copper (Cu)	7440-50-8		0.489	mg	1000000	288
				supplier	wire	Copper (Cu)	7440-50-8		0.489	mg	1000000	288
Encapsulation	Other Organic Materials	1090.671	mg	supplier	mold compound	Quartz	14808-60-7		763.470	mg	700000	449100
				supplier	mold compound	Silica, vitreous	60676-86-0		81.800	mg	75000	48118
				supplier	mold compound	Epoxy resin	25068-38-6		152.694	mg	140000	89820
				supplier	mold compound	phenol resin	29690-82-2		76.347	mg	70000	44910
				supplier	mold compound	metal hydroxide	21645-51-2		10.907	mg	10000	6416
				supplier	mold compound	carbon black	1333-86-4		5.453	mg	5000	3208
Connections coating	Solder	5.021	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.021	mg	1000000	2954